

ABSTRACT

5 A dicing/die-bonding integrated film according to an aspect of
the present disclosure includes a base material layer; an adhesive layer;
and a pressure-sensitive adhesive layer disposed between the base
material layer and the adhesive layer and having a first region in which
the tack force with respect to the adhesive layer has been decreased in
advance by irradiation with active energy rays, wherein the tack force of
the first region with respect to the adhesive layer is from 6.0 N/25 mm
to 12.5 N/25 mm as measured under the conditions of a peeling angle of
10 30° and a peeling speed of 60 mm/min at a temperature of 23°C.

Fig. 1